

AMENDMENTS

In the Claims

Cancel claims 4, 8, and 9 without prejudice, waiver, or disclaimer.

Please substitute the following clean copy text for the pending claims of the same number.

- sub D1
1. (Twice Amended) A microelectronic device package comprising:
a die attach pad, said pad having a bottom surface;
a plurality of substantially flat electrical connectors formed about a perimeter of said die attach pad, wherein said connectors are configured to couple a device to a substrate; and
an encapsulant surrounding a portion of said electrical connectors and a portion of said die attach pad, wherein said bottom surface of said die attach pad is substantially free of encapsulant.
- C1
sub E1
2. (Once Amended) The microelectronic device package according to claim 1, wherein said connectors and said pad are formed from a leadframe.
3. (Once Amended) The microelectronic device package according to claim 1, wherein said connectors and said pad are formed from an etched sheet of conductive material having removable material attached thereto.
- CD
5. (Twice Amended) The microelectronic device package according to claim 1, further comprising a coupling of a plurality of wires to one of said connectors.

Please add the following new claims:

- SUB
E17
21. (Newly Added) The microelectronic device package according to claim 1, wherein said pad is not offset from said connectors.
22. (Newly Added) The microelectronic device package according to claim 1, wherein said pad is configured to mechanically bond to a device.
- SUB
D2
23. (Newly Added) The microelectronic device package according to claim 5, wherein said wire is formed of gold wire having a diameter of approximately 25 microns.
- SUB
E17
MB
24. (Newly Added) The microelectronic device package according to claim 1, wherein bottom surface of said connectors is substantially free of encapsulant.
25. (Newly Added) The microelectronic device package according to claim 1, wherein said encapsulant is epoxy resin.
26. (Newly Added) The microelectronic device package according to claim 1, wherein the conductive path length through said connector is the thickness of said connector.
27. (Newly Added) The microelectronic device package according to claim 2, wherein said connectors and said die pad feature undercut regions to assist in attachment of said encapsulant.
28. (Newly Added) The microelectronic device package according to claim 3, wherein said connectors and said die pad feature undercut regions to assist in attachment of said encapsulant.
29. (Newly Added) The microelectronic device package according to claim 1, wherein portions of a device are electronically coupled to said die pad.

30. (Newly Added) The microelectronic device package according to claim 1, further comprising:

a coupling of a plurality of wires to said pad.

31. (Newly Added) The microelectronic device package according to claim 1, wherein said connectors are formed from a metal frame.

32. (Newly Added) The microelectronic device package according to claim 1, wherein said pad is formed from a metal frame.

33. (Newly Added) The microelectronic device package according to claims 31 or 32, wherein said frame is formed of copper.

34. (Newly Added) The microelectronic device package according to claims 31 or 32, wherein said frame is formed of a copper metal sheet having a thickness of approximately 200 microns.

35. (Newly Added) The microelectronic device package according to claim 30, wherein said frame is coated with about 10 micro inches of palladium.

36. (Newly Added) The microelectronic device package according to claim 22, wherein said device is bonded to said pad using conductive epoxy.

37. (Newly Added) The electronic device package according to claim 7, wherein said pad is not offset from said connectors.

38. (Newly Added) The electronic device package according to claim 7, wherein said pad is configured to mechanically bond to a device.

39. (Newly Added) The electronic device package according to claim 6, further comprising:

a coupling of a plurality of wires to one of said connectors.

40. (Newly Added) The electronic device package according to claim 39, wherein said wire is formed of gold wire having a diameter of approximately 25 μm .
41. (Newly Added) The electronic device package according to claim 6, wherein bottom surface of said connectors is substantially free of encapsulant.
42. (Newly Added) The electronic device package according to claim 6, wherein said encapsulant is epoxy resin.
43. (Newly Added) The electronic device package according to claim 6, wherein the conductive path length through said connector is the thickness of said connector.
44. (Newly Added) The electronic device package according to claim 7, wherein said connectors and said die pad feature undercut regions to assist in attachment of said encapsulant.
45. (Newly Added) The electronic device package according to claim 7, wherein portions of a device are electronically coupled to said die pad.
46. (Newly Added) The electronic device package according to claim 7, further comprising:
a coupling of a plurality of wires to said pad.
47. (Newly Added) The electronic device package according to claim 6, wherein said connectors are formed from a metal frame.
48. (Newly Added) The electronic device package according to claim 7, wherein said pad is formed from a metal frame.
49. (Newly Added) The electronic device package according to claims 47 or 48, wherein said frame is formed of copper.

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